

Product Change Notification - GBNG-06THAP224

Date: 23 May 2017

Product Category: Digital Potentiometers; System D/A Converters; Linear Op Amps; Linear Comparators; Real-Time Clock/Calendar; 8-bit PIC Microcontrollers; Piezoelectric Horn Drivers; Frequency-to-Voltage / Voltage-to-Frequency Converters; Capacitive Touch Sensors; KEELOQ® Encoder Devices; KEELOQ® Decoder Devices; Interface- LIN Transceiver; Touch Controllers; Interface- Infrared Products; Interface- Controller Area Network (CAN); Successive Approximation Register (SAR) A/D Converters; Sigma - Delta A/D Converters

Notification subject: CCB 2851 Final Notice: Qualification of 98 x 235 mils lead frame paddle size available in selected 14L SOIC package at MMT assembly site.

Notification text: **PCN Status:**
Final notification

Microchip Parts Affected:

Please open the attachments found in the attachments field below labeled as PCN_#_Affected_CPN.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:

Qualification of 98 x 235 mils lead frame paddle size available in selected 14L SOIC package at MMT assembly site.

Pre Change:

Assembled at MMT using lead frame with 90 x 110 mils paddle size and at MTAI using 90 x 90, 95 x 155 and 98 x 235 mils lead frame paddle sizes.

Post Change:

Assembled at MMT or MTAI using 90 x 90, 95 x 155 and 98 x 235 mils lead frame paddle sizes.

Pre and Post Change Summary:

	Pre Change		Post Change
Assembly Site	MTAI	MMT	MTAI or MMT
Wire material	Au wire	Au wire	Au wire
Die attach material	8390A	8390A	8390A
Molding compound material	G600	G600	G600
Lead frame material	CDA194	CDA194	CDA194
Lead frame paddle size	90 x 90 mils		90 x 90 mils
	95 x 155 mils	90 x 110 mils	95 x 155 mils
	98 x 235 mils		98 x 235 mils

Impacts to Data Sheet:

None

Change Impact:

None

Reason for Change:

To improve productivity by qualifying 98 x 235 mils lead frame paddle size at MMT assembly site.

Change Implementation Status:

In Progress

Estimated First Ship Date :

June 23, 2017 (date code: 1725)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:

	February 2017					-->	May 2017					June 2017			
Workweek	05	06	07	08	09		18	19	20	21	22	23	24	25	26
Initial PCN Issue Date			X												
Qual Report Availability								X							
Final PCN Issue Date								X							
Estimated Implementation Date														X	

Qualification Report:Method to Identify Change:

Traceability code

Please open the attachments included with this PCN labeled as PCN_#_Qual Report.

Revision History:

February 17, 2017: Issued initial notification.

February 24, 2017: Re-issued initial notification to revise affected CPN list.

May 23, 2017: Issued final notification. Attached the Qualification Report. Revised the affected parts list. Provided estimated first ship date on June 23, 2017.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):

[PCN_GBNG-06THAP224_Affected CPN.pdf](#)

[PCN_GBNG-06THAP224_Qual Report.pdf](#)

[PCN_GBNG-06THAP224_Affected CPN.xlsx](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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GBNG-06THAP224 - CCB 2851 Final Notice: Qualification of 14L SOIC package with 98 x 235 mils lead frame paddle size for selected products at MMT assembly site.

Affected Catalog Part Numbers (CPN)

PCN_GBNG-06THAP224
CATALOG_PART_NBR
CAP1206-1-SL
CAP1206-1-SL-TR
CAP1206-2-SL-TR
CAP1208-1-SL
CAP1208-1-SL-TR
CAP1208-2-SL-TR
CAP1296-1-SL
CAP1296-1-SL-TR
CAP1296-2-SL-TR
CAP1298-1-SL
CAP1298-1-SL-TR
CAP1298-2-SL-TR
HA1086-I/SL
HA1086T-I/SL
HA1504-I/SL
HA1504T-I/SL
HA2038-I/SL
HA2089-I/SL
HA2089-I/SL108
HA2089-I/SL109
HA2089T-I/SL
HA2089T-I/SL040
HA2089T-I/SL043
HA2089T-I/SL054
HA2089T-I/SL057
HA2089T-I/SL077
HA2089T-I/SL086
HA2089T-I/SL097
HA2089T-I/SL100
HA2089T-I/SL103
HA2089T-I/SL104
HA2089T-I/SL106
HA2089T-I/SL108
HA2089T-I/SL109
HCS370/SL
HCS370-I/SL
HCS370T/SL
HCS370T-I/SL
HCS515/SL
HCS515-I/SL
HCS515-I/SLA56
HCS515T/SL
HCS515T-I/SL

GBNG-06THAP224 - CCB 2851 Final Notice: Qualification of 14L SOIC package with 98 x 235 mils lead frame paddle size for selected products at MMT assembly site.

Affected Catalog Part Numbers (CPN)

PCN_GBNG-06THAP224
CATALOG_PART_NBR
HV9120NG-G
HV9120NG-G-M901
MCP2022-330E/SL
MCP2022-500E/SL
MCP2022A-330E/SL
MCP2022A-500E/SL
MCP2022AT-330E/SL
MCP2022AT-500E/SL
MCP2022P-330E/SL
MCP2022P-500E/SL
MCP2022PT-330E/SL
MCP2022PT-500E/SL
MCP2022T-330E/SL
MCP2022T-500E/SL
MCP2036-I/SL
MCP2036T-I/SL
MCP2050-330E/SL
MCP2050-500E/SL
MCP2050T-330E/SL
MCP2050T-500E/SL
MCP2120-I/SL
MCP2120T-I/SL
MCP25612FD-E/SL
MCP25612FD-H/SL
MCP25612FDT-E/SL
MCP25612FDT-H/SL
MCP3204-BI/SL
MCP3204-CI/SL
MCP3204T-BI/SL
MCP3204T-CI/SL
MCP3424-E/SL
MCP3424T-E/SL
MCP3428-E/SL
MCP3428T-E/SL
MCP4231-103E/SL
MCP4231-104E/SL
MCP4231-502E/SL
MCP4231-503E/SL
MCP4231T-103E/SL
MCP4231T-104E/SL
MCP4231T-502E/SL
MCP4231T-503E/SL
MCP4241-103E/SL

GBNG-06THAP224 - CCB 2851 Final Notice: Qualification of 14L SOIC package with 98 x 235 mils lead frame paddle size for selected products at MMT assembly site.

Affected Catalog Part Numbers (CPN)

PCN_GBNG-06THAP224
CATALOG_PART_NBR
MCP4241-104E/SL
MCP4241-502E/SL
MCP4241-503E/SL
MCP4241T-103E/SL
MCP4241T-104E/SL
MCP4241T-502E/SL
MCP4241T-503E/SL
MCP4251-103E/SL
MCP4251-104E/SL
MCP4251-502E/SL
MCP4251-503E/SL
MCP4251T-103E/SL
MCP4251T-104E/SL
MCP4251T-502E/SL
MCP4251T-503E/SL
MCP4261-103E/SL
MCP4261-104E/SL
MCP4261-502E/SL
MCP4261-503E/SL
MCP4261T-103E/SL
MCP4261T-104E/SL
MCP4261T-502E/SL
MCP4261T-503E/SL
MCP4902-E/SL
MCP4902T-E/SL
MCP4912-E/SL
MCP4912T-E/SL
MCP4922-E/SL
MCP4922T-E/SL
MCP6004-E/SL
MCP6004-I/SL
MCP6004-I/SLB21
MCP6004T-E/SL
MCP6004T-I/SL
MCP6004T-I/SLB21
MCP6034-E/SL
MCP6034T-E/SL
MCP6034T-E/SLV01
MCP6044-E/SL
MCP6044-E/SLBAA
MCP6044-I/SL
MCP6044T-E/SL
MCP6044T-E/SLBAA

GBNG-06THAP224 - CCB 2851 Final Notice: Qualification of 14L SOIC package with 98 x 235 mils lead frame paddle size for selected products at MMT assembly site.

Affected Catalog Part Numbers (CPN)

PCN_GBNG-06THAP224
CATALOG_PART_NBR
MCP6044T-I/SL
MCP604-E/SL
MCP604-I/SL
MCP604T-E/SL
MCP604T-I/SL
MCP6054-E/SL
MCP6054T-E/SL
MCP6064-E/SL
MCP6064T-E/SL
MCP6074-E/SL
MCP6074T-E/SL
MCP6234-E/SL
MCP6234T-E/SL
MCP6244-E/SL
MCP6244T-E/SL
MCP624-E/SL
MCP624T-E/SL
MCP6274-E/SL
MCP6274-E/SLB21
MCP6274T-E/SL
MCP6274T-E/SLB21
MCP6284-E/SL
MCP6284-E/SLDAA
MCP6284T-E/SL
MCP6284T-E/SLDAA
MCP6294-E/SL
MCP6294T-E/SL
MCP634-E/SL
MCP634T-E/SL
MCP6404-E/SL
MCP6404-H/SL
MCP6404T-E/SL
MCP6404T-H/SL
MCP6409-H/SL
MCP6409T-H/SL
MCP654-E/SL
MCP654T-E/SL
MCP6564-E/SL
MCP6564T-E/SL
MCP6569-E/SL
MCP6569T-E/SL
MCP660-E/SL
MCP660T-E/SL

GBNG-06THAP224 - CCB 2851 Final Notice: Qualification of 14L SOIC package with 98 x 235 mils lead frame paddle size for selected products at MMT assembly site.

Affected Catalog Part Numbers (CPN)

PCN_GBNG-06THAP224
CATALOG_PART_NBR
MCP664-E/SL
MCP664T-E/SL
MCP6H04-E/SL
MCP6H04T-E/SL
MCP6H74-E/SL
MCP6H74T-E/SL
MCP6H84-E/SL
MCP6H84T-E/SL
MCP6H94-E/SL
MCP6H94T-E/SL
MCP6L04T-E/SL
MCP6L4T-E/SL
MCP6L74T-E/SL
MCP6L94T-E/SL
MCP795W10-I/SL
MCP795W10T-I/SL
MCP795W11-I/SL
MCP795W11T-I/SL
MCP795W12-I/SL
MCP795W12T-I/SL
MCP795W20-I/SL
MCP795W20T-I/SL
MCP795W21-I/SL
MCP795W21T-I/SL
MCP795W22-I/SL
MCP795W22T-I/SL
MCV14A-I/SL
MCV14A-I/SL029
MCV14A-I/SL032
MCV14A-I/SL037
MCV14A-I/SL038
MCV14A-I/SL039
MCV14A-I/SL040
MCV14A-I/SL042
MCV14A-I/SL043
MCV14A-I/SL044
MCV14A-I/SL045
MCV14A-I/SL046
MCV14A-I/SL049
MCV14A-I/SL050
MCV14A-I/SL051
MCV14A-I/SL052
MCV14A-I/SL054

GBNG-06THAP224 - CCB 2851 Final Notice: Qualification of 14L SOIC package with 98 x 235 mils lead frame paddle size for selected products at MMT assembly site.

Affected Catalog Part Numbers (CPN)

PCN_GBNG-06THAP224
CATALOG_PART_NBR
MCV14A-I/SL060
MCV14A-I/SL062
MCV14A-I/SL063
MCV14A-I/SL064
MCV14A-I/SL065
MCV14A-I/SL066
MCV14AT-I/SL
MCV14AT-I/SL021
MCV14AT-I/SL025
MCV14AT-I/SL029
MCV14AT-I/SL032
MCV14AT-I/SL035
MCV14AT-I/SL037
MCV14AT-I/SL038
MCV14AT-I/SL039
MCV14AT-I/SL040
MCV14AT-I/SL042
MCV14AT-I/SL043
MCV14AT-I/SL044
MCV14AT-I/SL045
MCV14AT-I/SL046
MCV14AT-I/SL049
MCV14AT-I/SL050
MCV14AT-I/SL051
MCV14AT-I/SL052
MCV14AT-I/SL054
MCV14AT-I/SL055
MCV14AT-I/SL057
MCV14AT-I/SL058
MCV14AT-I/SL060
MCV14AT-I/SL062
MCV14AT-I/SL063
MCV14AT-I/SL064
MCV14AT-I/SL065
MCV14AT-I/SL066
PIC16C505-04/SL
PIC16C505-04/SLC01
PIC16C505-04E/SL
PIC16C505-04I/SL
PIC16C505-20/SL
PIC16C505-20E/SL
PIC16C505-20I/SL
PIC16C505T-04/SL

GBNG-06THAP224 - CCB 2851 Final Notice: Qualification of 14L SOIC package with 98 x 235 mils lead frame paddle size for selected products at MMT assembly site.

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PCN_GBNG-06THAP224
CATALOG_PART_NBR
PIC16C505T-04/SL098
PIC16C505T-04E/SL
PIC16C505T-04E/SL115
PIC16C505T-04I/SL
PIC16C505T-04I/SL060
PIC16C505T-04I/SL111
PIC16C505T-04I/SL137
PIC16C505T-20/SL
PIC16C505T-20E/SL
PIC16C505T-20I/SL
PIC16F1454-E/SL
PIC16F1454-I/SL
PIC16F1454-I/SLC01
PIC16F1454T-I/SL
PIC16F1454T-I/SL023
PIC16F1454T-I/SLC01
PIC16F15323-E/SL
PIC16F15323-I/SL
PIC16F15323T-I/SL
PIC16F15324-E/SL
PIC16F15324-I/SL
PIC16F15324T-I/SL
PIC16F15325-E/SL
PIC16F15325-I/SL
PIC16F15325T-I/SL
PIC16F1613-E/SL
PIC16F1613-I/SL
PIC16F1613T-I/SL
PIC16F1703-E/SL
PIC16F1703-I/SL
PIC16F1703T-I/SL
PIC16F1823-E/SL
PIC16F1823-I/SL
PIC16F1823-I/SL024
PIC16F1823-I/SL037
PIC16F1823-I/SLC04
PIC16F1823T-E/SL
PIC16F1823T-I/SL
PIC16F1823T-I/SL024
PIC16F1823T-I/SL025
PIC16F1823T-I/SL026
PIC16F1823T-I/SL037
PIC16F1823T-I/SL038

GBNG-06THAP224 - CCB 2851 Final Notice: Qualification of 14L SOIC package with 98 x 235 mils lead frame paddle size for selected products at MMT assembly site.

Affected Catalog Part Numbers (CPN)

PCN_GBNG-06THAP224
CATALOG_PART_NBR
PIC16F1823T-I/SLC04
PIC16F18323-E/SL
PIC16F18323-I/SL
PIC16F18323-I/SLJIN
PIC16F18323T-E/SL
PIC16F18323T-I/SL
PIC16F18324-E/SL
PIC16F18324-I/SL
PIC16F18324T-I/SL
PIC16F18325-E/SL
PIC16F18325-I/SL
PIC16F18325T-I/SL
PIC16F18326-E/SL
PIC16F18326-I/SL
PIC16F18326T-I/SL
PIC16F505-E/SL
PIC16F505-I/SL
PIC16F505-I/SL023
PIC16F505-I/SL033
PIC16F505-I/SL059
PIC16F505T-E/SL
PIC16F505T-I/SL
PIC16F505T-I/SL020
PIC16F505T-I/SL029
PIC16F505T-I/SL033
PIC16F505T-I/SL039
PIC16F505T-I/SL054
PIC16F505T-I/SL055
PIC16F505T-I/SL056
PIC16F505T-I/SL058
PIC16F505T-I/SL059
PIC16F505T-I/SL062
PIC16F505T-I/SLC03
PIC16F506-E/SL
PIC16F506-I/SL
PIC16F506T-I/SL
PIC16F506T-I/SL021
PIC16F506T-I/SL030
PIC16F506T-I/SL034
PIC16F506T-I/SL039
PIC16F506T-I/SL042
PIC16F506T-I/SL043
PIC16F506T-I/SL044

GBNG-06THAP224 - CCB 2851 Final Notice: Qualification of 14L SOIC package with 98 x 235 mils lead frame paddle size for selected products at MMT assembly site.

Affected Catalog Part Numbers (CPN)

PCN_GBNG-06THAP224
CATALOG_PART_NBR
PIC16F506T-I/SL047
PIC16F526-E/SL
PIC16F526-I/SL
PIC16F526-I/SLC03
PIC16F526-I/SLC04
PIC16F526-I/SLC06
PIC16F526T-I/SL
PIC16F526T-I/SL033
PIC16F526T-I/SL034
PIC16F526T-I/SL053
PIC16F526T-I/SL061
PIC16F526T-I/SLC04
PIC16F526T-I/SLC06
PIC16F610-E/SL
PIC16F610-I/SL
PIC16F610T-I/SL
PIC16F616-E/SL
PIC16F616-E/SL087
PIC16F616-H/SL
PIC16F616-I/SL
PIC16F616-I/SL063
PIC16F616-I/SL068
PIC16F616T-E/SL
PIC16F616T-E/SL040
PIC16F616T-E/SL072
PIC16F616T-E/SL083
PIC16F616T-E/SL084
PIC16F616T-E/SL087
PIC16F616T-I/SL
PIC16F616T-I/SL029
PIC16F616T-I/SL033
PIC16F616T-I/SL038
PIC16F616T-I/SL048
PIC16F616T-I/SL050
PIC16F616T-I/SL054
PIC16F616T-I/SL055
PIC16F616T-I/SL063
PIC16F616T-I/SL064
PIC16F616T-I/SL068
PIC16F616T-I/SL069
PIC16F616T-I/SL074
PIC16F616T-I/SL077
PIC16F616T-I/SL086

GBNG-06THAP224 - CCB 2851 Final Notice: Qualification of 14L SOIC package with 98 x 235 mils lead frame paddle size for selected products at MMT assembly site.

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PCN_GBNG-06THAP224
CATALOG_PART_NBR
PIC16F616T-I/SL089
PIC16F616T-I/SL091
PIC16F616T-I/SL092
PIC16F616T-I/SL094
PIC16F616T-I/SL095
PIC16F630-C/SL
PIC16F630-E/SL
PIC16F630-I/SL
PIC16F630-I/SL036
PIC16F630-I/SL044
PIC16F630-I/SL045
PIC16F630-I/SLC03
PIC16F630T-C/SL
PIC16F630T-E/SL
PIC16F630T-E/SL072
PIC16F630T-I/SL
PIC16F630T-I/SL026
PIC16F630T-I/SL035
PIC16F630T-I/SL043
PIC16F630T-I/SL053
PIC16F630T-I/SL066
PIC16F630T-I/SL080
PIC16F630T-I/SL081
PIC16F630T-I/SL082
PIC16F636-E/SL
PIC16F636-I/SL
PIC16F636T-E/SL
PIC16F636T-I/SL
PIC16F636T-I/SL022
PIC16F676-E/SL
PIC16F676-I/SL
PIC16F676-I/SL045
PIC16F676-I/SL050
PIC16F676-I/SL051
PIC16F676T-C/SL
PIC16F676T-E/SL
PIC16F676T-I/SL
PIC16F676T-I/SL028
PIC16F676T-I/SL038
PIC16F676T-I/SL044
PIC16F676T-I/SL051
PIC16F684-E/SL
PIC16F684-I/SL

GBNG-06THAP224 - CCB 2851 Final Notice: Qualification of 14L SOIC package with 98 x 235 mils lead frame paddle size for selected products at MMT assembly site.

Affected Catalog Part Numbers (CPN)

PCN_GBNG-06THAP224
CATALOG_PART_NBR
PIC16F684-I/SL105
PIC16F684-I/SLC15
PIC16F684-I/SLC17
PIC16F684T-E/SL
PIC16F684T-I/SL
PIC16F684T-I/SL027
PIC16F684T-I/SL028
PIC16F684T-I/SL088
PIC16F684T-I/SL091
PIC16F684T-I/SL094
PIC16F684T-I/SL095
PIC16F684T-I/SL099
PIC16F684T-I/SL105
PIC16F684T-I/SLC15
PIC16F684T-I/SLC17
PIC16F753-E/SL
PIC16F753-I/SL
PIC16F753-I/SLC02
PIC16F753-I/SLPN1
PIC16F753-I/SLSM1
PIC16F753-I/SLSM2
PIC16F753T-I/SL
PIC16F753T-I/SL020
PIC16F753T-I/SLC02
PIC16F753T-I/SLHS2
PIC16F753T-I/SLPN1
PIC16F753T-I/SLSM1
PIC16F753T-I/SLSM2
PIC16HV610-E/SL
PIC16HV610-I/SL
PIC16HV610T-I/SL
PIC16HV616-E/SL
PIC16HV616-I/SL
PIC16HV616T-E/SL
PIC16HV616T-I/SL
PIC16HV753-E/SL
PIC16HV753-I/SL
PIC16HV753T-E/SL
PIC16HV753T-I/SL
PIC16LC505-04/SL
PIC16LC505-04I/SL
PIC16LC505T-04/SL
PIC16LC505T-04I/SL

GBNG-06THAP224 - CCB 2851 Final Notice: Qualification of 14L SOIC package with 98 x 235 mils lead frame paddle size for selected products at MMT assembly site.

Affected Catalog Part Numbers (CPN)

PCN_GBNG-06THAP224
CATALOG_PART_NBR
PIC16LF1454-E/SL
PIC16LF1454-I/SL
PIC16LF1454T-I/SL
PIC16LF1455-E/SL
PIC16LF1455-I/SL
PIC16LF1455T-I/SL
PIC16LF15323-E/SL
PIC16LF15323-I/SL
PIC16LF15323T-I/SL
PIC16LF15324-E/SL
PIC16LF15324-I/SL
PIC16LF15324T-I/SL
PIC16LF15325-E/SL
PIC16LF15325-I/SL
PIC16LF15325T-I/SL
PIC16LF1554-E/SL
PIC16LF1554-I/SL
PIC16LF1554T-I/SL
PIC16LF1613-E/SL
PIC16LF1613-I/SL
PIC16LF1613T-I/SL
PIC16LF1703-E/SL
PIC16LF1703-I/SL
PIC16LF1703T-I/SL
PIC16LF1823-E/SL
PIC16LF1823-I/SL
PIC16LF1823-I/SLC03
PIC16LF1823T-E/SL
PIC16LF1823T-I/SL
PIC16LF1823T-I/SL023
PIC16LF1823T-I/SLC03
PIC16LF1824-E/SL
PIC16LF1824-I/SL
PIC16LF1824-I/SLC01
PIC16LF1824T-E/SL
PIC16LF1824T-I/SL
PIC16LF1824T-I/SL026
PIC16LF1824T-I/SL027
PIC16LF1824T-I/SL028
PIC16LF1824T-I/SLC01
PIC16LF18323-E/SL
PIC16LF18323-I/SL
PIC16LF18323T-E/SL

GBNG-06THAP224 - CCB 2851 Final Notice: Qualification of 14L SOIC package with 98 x 235 mils lead frame paddle size for selected products at MMT assembly site.

Affected Catalog Part Numbers (CPN)

PCN_GBNG-06THAP224
CATALOG_PART_NBR
PIC16LF18323T-I/SL
PIC16LF18323T-I/SLC01
PIC16LF18324-E/SL
PIC16LF18324-I/SL
PIC16LF18324T-I/SL
PIC16LF18324T-I/SLO20
PIC16LF18325-E/SL
PIC16LF18325-I/SL
PIC16LF18325T-I/SL
PIC16LF18326-E/SL
PIC16LF18326-I/SL
PIC16LF18326T-I/SL
RE46C104S14F
RE46C104S14TF
RE46C105S14F
RE46C105S14TF
TC9400COD
TC9400COD713
TC9400EOD
TC9400EOD713
TC9400IOD



MICROCHIP

QUALIFICATION REPORT SUMMARY
RELIABILITY LABORATORY

PCN#: GBNG-06THAP224

Date
April 19, 2017

**Qualification of 98 x 235 mils lead frame paddle size available
in selected 14L SOIC package at MMT assembly site.**



MICROCHIP PACKAGE QUALIFICATION REPORT

Purpose	Qualification of 98 x 235 mils lead frame paddle size available in selected 14L SOIC package at MMT assembly site.
CN	ES090530-18926
QUAL ID	Q17030
MP CODE	A5AJ17D3X370
Part No.	HCS370-I/SL
Bonding No.	BDM-001273 Rev. A
CCB No.	2851

Package

Type	14L SOIC
Package size	150 mils
Die thickness	15 mils
Die size	143.0 x 90.90 mils

Lead Frame

Paddle size	98 x 235 mils
Material	CDA194
Surface	Ag Spot Plated
Process	Stamped
Lead Lock	No
Part Number	10101403
Treatment	None

Material

Epoxy	8390A
Wire	Au wire
Mold Compound	G600V
Plating Composition	Matte Tin



MICROCHIP PACKAGE QUALIFICATION REPORT

Manufacturing Information

Assembly Lot No.	Wafer Lot No.	Date Code
MMT-173900823.000	TMPE217295353.B00	1706RCC
MMT-174600827.000	TMPE217295353.B00	1706TTC
MMT-174700448.000	TMPE217295353.B00	1707TTE

Result

Pass Fail _____

14L SOIC (.150") assembled by MMT (ALPH) pass reliability test per QCI-39000.
This package was qualified the Moisture/Reflow Sensitivity Classification Level 1 at 260°C
reflow temperature per IPC/JEDEC J-STD-020D standard.

PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS	Result	Remarks
Moisture/Reflow Sensitivity Classification Test (At MSL Level 1)	85°C/ 85%RH Moisture Soak 168 hrs. System: TABAI ESPEC Model PR-3SPH 3x Convection-Reflow 265°C max System: Vitronics Soltec MR1243 (IPC/JEDEC J-STD-020D)	IPC/JEDEC C J-STD-020D	135	0/135	Pass	

Precondition Prior Perform Reliability Tests (At MSL Level 1)	Electrical Test :+25°C and 85°C System: J750	JESD22-A113	693(0)	693	Pass	Good Devices
	Bake 150°C, 24 hrs System: CHINEE			693		
	85°C/85%RH Moisture Soak 168 hrs. System: TABAI ESPEC Model PR-3SPH			693		
	3x Convection-Reflow 265°C max System: Vitronics Soltec MR1243			693		
	Electrical Test :+25°C and 85°C System: J750			0/693		

PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS.	Result	Remarks
Temp Cycle	Stress Condition: -65°C to +150°C, 500 Cycles System : TABAI ESPEC TSA-70H	JESD22- A104	231(0)	231	Pass	Parts had been pre-conditioned at 260°C 77 units / lot
	Electrical Test: + 85°C System: J750			0/231		
	Bond Strength: Wire Pull (> 2.5 grams) Bond Shear (>15.00 grams)			15 (0) 0/15 15 (0) 0/15		
UNBIASED-HAST	Stress Condition: +130°C/85%RH, 96 hrs. System: HAST 6000X	JESD22- A118	231(0)	231	Pass	Parts had been pre-conditioned at 260°C 77 units / lot
	Electrical Test: +25°C System: J750			0/231		
HAST	Stress Condition: +130°C/85%RH, 96 hrs. Bias Volt: 5.5 Volts System: HAST 6000X	JESD22- A110	231(0)	231	Pass	Parts had been pre-conditioned at 260°C 77 units / lot
	Electrical Test: +25°C and 85°C System: J750			0/231		
High Temperature Storage Life	Stress Condition: Bake 175°C, 504 hrs System: SHEL LAB	JESD22- A103	45(0)	45	Pass	45 units
	Electrical Test :+25°C and 85°C System: J750			0/45		

PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS.	Result	Remarks
Bond Strength Data Assembly	Wire Pull (> 2.5 grams)	M2011	30 (0) Wires	0/30	Pass	
	Bond Shear (>15.00 grams)	JESD22- B116	30 (0) bonds	0/30	Pass	

